Seica and Reid-Ashman Collaborate to Showcase Innovative Test Integration at productronica 2025

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Booth A1-538

Seica S.p.A., a global leader in electronic test solutions, and Reid-Ashman Manufacturing, Inc., a world-leading provider of test head manipulators and interfacing solutions, are pleased to announce a collaboration that brings together two pillars of innovation in the electronics test industry. At **productronica 2025** in Munich, visitors to **Booth A1-538** will see Seica's latest **S20 IS³ Power Semiconductor Test System** mounted on a Reid-Ashman manipulator, demonstrating an integrated platform that combines precision testing with safe, efficient handling.

The joint display highlights how the two companies' technologies complement one another to deliver greater productivity, reliability, and usability in semiconductor device testing. Seica's S20 IS³ is a compact, all-in-one test platform designed for the static and dynamic testing of discrete power devices such as IGBTs, MOSFETs, and diodes, including SiC and GaN technologies. By integrating DC-static, gate, and AC-dynamic test modules in a single system, the S20 IS³ provides full electrical characterization of key parameters such as on-state voltage, leakage current, threshold voltage, and switching behavior. The system's modular and scalable design makes it ideal for applications ranging from R&D to volume production, ensuring repeatable, traceable, and highly accurate measurements.

Supporting this advanced test platform is a Reid-Ashman manipulator, engineered to provide precise and effortless positioning of heavy test heads with complete operator safety. Recognized globally as a leader in test head manipulator manufacturing, Reid-Ashman's designs are known for their stability, reliability, and space-efficient form. The integration of the S20 IS³ on a Reid-Ashman manipulator allows for repeatable alignment and connection, shorter setup times, and a more ergonomic operator experience. Together, the systems create a fully optimized testing environment that combines electrical precision with mechanical control.

"With automation and test head handling becoming ever more critical in today's accelerated device lifecycles, this collaboration is a tangible demonstration of how mechanical innovation and electrical test engineering can combine to deliver superior productivity and usability," said Mr. David Sigillo, Seica Inc. Vice President. Chris McArthur Account Manager, Reid-Ashman added, "Our manipulators easily integrate with the world's leading ATE and power test platforms. Partnering with Seica shows how robust mechanical systems can complement advanced test technology to provide a complete, ergonomic solution for semiconductor testing."

Visitors to productronica 2025 are invited to Booth A1-538 to experience this integration firsthand. The demonstration will showcase smooth test head motion, precise alignment, fast device changeover, and the full software integration of Seica's VIVA™ platform, which manages data collection, traceability, and MES communication. The result is a cohesive solution that reflects both companies' commitment to innovation, reliability, and user-centered design.

Founded on decades of expertise, Seica S.p.A. continues to lead in developing smart, high-performance test solutions for electronic boards, modules, and semiconductors. Reid-Ashman Manufacturing, headquartered in St. George, Utah, is a leader in manipulator and docking system design, offering vertically integrated manufacturing that ensures quick setup, long-term reliability, and optimal performance across global test environments.

About Seica

The Seica Group is a global provider of high-technology turnkey solutions for the industrial sector, offering systems for electronic board testing, semiconductor testing, industrial automation, laser selective soldering, and optical inspection. Founded in 1986, Seica S.p.A. designs and manufactures advanced test systems, including automotive and electric vehicle applications, and provides dedicated solutions for high-density probe card testing. Seica also develops systems and applications for the defense and aerospace sectors, meeting the most rigorous standards. Embracing Industry 4.0 and 5.0, the Group creates smart systems that collect and analyze data to improve production, maintenance, and energy efficiency. Headquartered in Italy, Seica has offices in Germany, France, China, the USA, Mexico, and Israel.

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